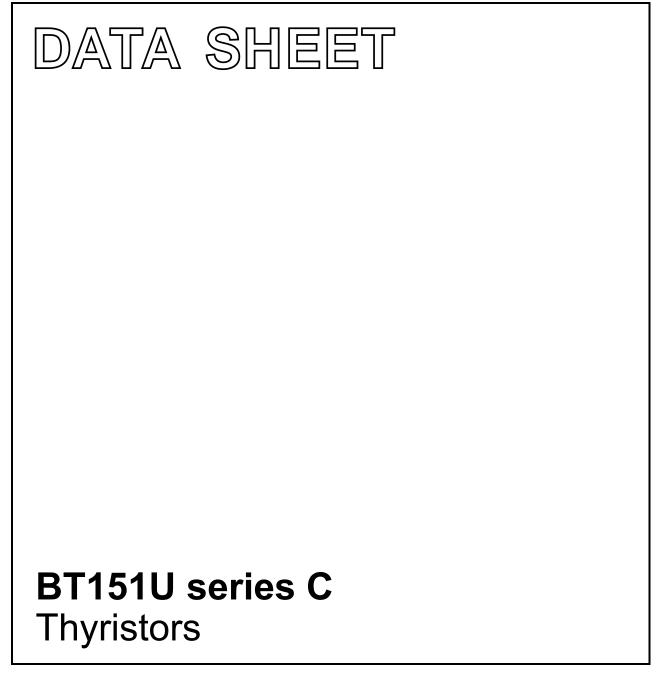
DISCRETE SEMICONDUCTORS



Product specification

April 2004



BT151U series C

GENERAL DESCRIPTION

Passivated thyristors in a plastic envelope, intended for use in applications requiring high bidirectional blocking voltage capability and high thermal cycling performance. Typical applications include motor control, industrial and domestic lighting, heating and static switching.

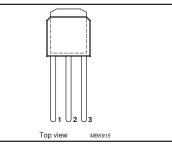
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	MAX.	UNIT
$V_{DRM}, \\ V_{RRM} \\ I_{T(AV)} \\ I_{T(RMS)} \\ I_{TSM}$	BT151U- Repetitive peak off-state voltages Average on-state current RMS on-state current Non-repetitive peak on-state current	500C 500 7.5 12 100	650C 650 7.5 12 100	800C 800 7.5 12 100	V A A A

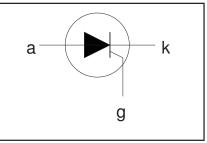
PINNING - SOT533, (I-PAK)

PIN NUMBER	DESCRIPTION
1	cathode
2	anode
3	gate
tab	anode

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.		UNIT	
$V_{\text{drm}}, V_{\text{rrm}}$	Repetitive peak off-state voltages		-	-500C 500 ¹	-650C 650 ¹	-800C 800	V
I _{T(AV)} I _{T(RMS)} I _{TSM}	Average on-state current RMS on-state current Non-repetitive peak on-state current	half sine wave; $T_{mb} \le 104$ °C all conduction angles half sine wave; $T_j = 25$ °C prior to surge	-		7.5 12		A A
		t = 10 ms t = 8.3 ms	-		100 110		A A
l²t dI _⊤ /dt	I ² t for fusing Repetitive rate of rise of on-state current after	t = 10 ms I _{TM} = 20 A; I _G = 50 mA; dI _G /dt = 50 mA/μs	-		50 50		A²s A/μs
I _{GM} V _{RGM} P _{GM}	triggering Peak gate current Peak reverse gate voltage Peak gate power				2 5 5		A V W
$\begin{array}{c} P_{G(AV)}\\ P_{G(AV)}\\ T_{stg}\\ T_{j} \end{array}$	Average gate power Storage temperature Junction temperature	over any 20 ms period	-40 -		0.5 150 125		°℃ Q

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15 A/ μ s.

BT151U series C

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-mb}	Thermal resistance junction to mounting base		-	-	1.3	K/W K/W
R _{th j-a}	Thermal resistance junction to ambient	in free air	-	70	-	K/W

STATIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

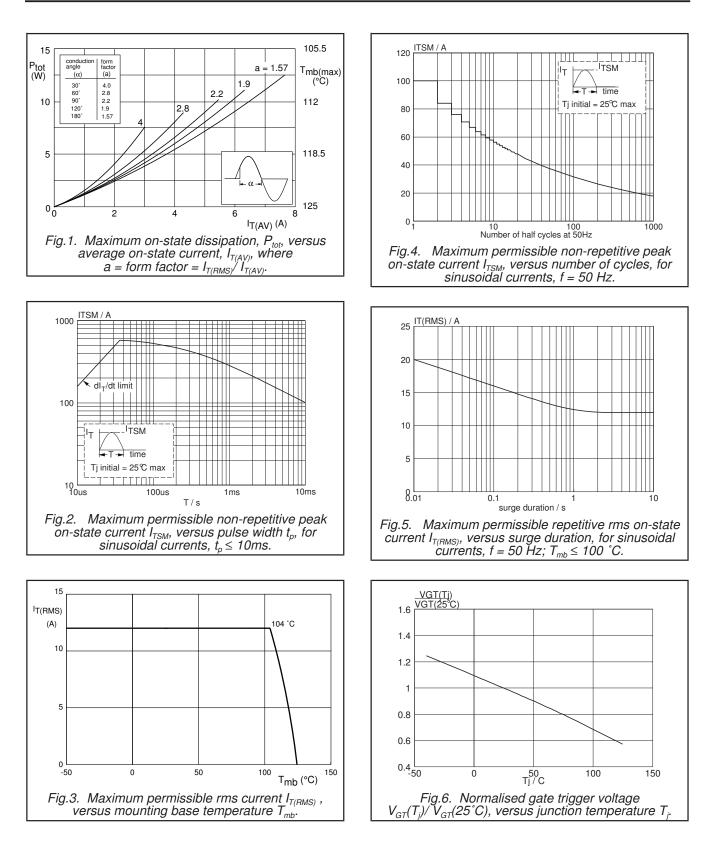
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{GT}	Gate trigger current	$V_{\rm D} = 12 \text{ V}; \text{ I}_{\rm T} = 0.1 \text{ A}$	-	2	15	mA
	Latching current	$V_{\rm D} = 12 \text{ V}; \text{ I}_{\rm GT} = 0.1 \text{ A}$	-	10	40	mA
I I _H	Holding current	$V_{\rm D} = 12 \text{ V}; I_{\rm GT} = 0.1 \text{ A}$	-	7	20	mA
İ Ϋ _T	On-state voltage	$I_{T} = 23 \text{ A}$	-	1.44	1.75	V
V _{GT}	Gate trigger voltage	$\dot{V}_{\rm D} = 12 \text{ V}; \text{ I}_{\rm T} = 0.1 \text{ A}$	-	0.6	1.5	V
		$V_{D} = V_{DRM(max)}; I_{T} = 0.1 \text{ A}; T_{j} = 125 \text{ °C}$	0.25	0.4	-	V
I _D , I _R	Off-state leakage current	$V_D = V_{DRM(max)}^{Orthm(max)}; V_R = V_{RRM(max)}; T_j = 125 \text{°C}$	-	0.1	0.5	mA

DYNAMIC CHARACTERISTICS

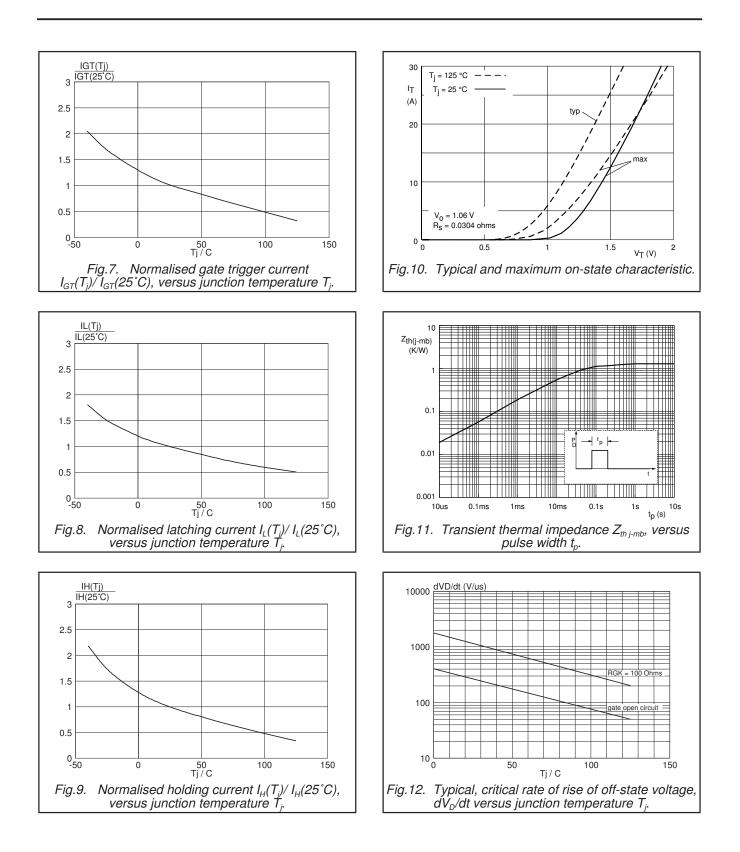
$T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV _D /dt	Critical rate of rise of off-state voltage	$V_{DM} = 67\% V_{DRM(max)}; T_j = 125 °C;$ exponential waveform Gate open circuit	50 200	130 1000	-	V/µs
t _{gt}	Gate controlled turn-on time	$ \begin{array}{l} R_{GK}^{-} = 100 \ \Omega \\ I_{TM}^{-} = 40 \ A; \ V_{D}^{-} = V_{DRM(max)}; \ I_{G}^{-} = 0.1 \ A; \\ dI_{G}^{-} dI_{G}^{-} dI_{G}^{-} = 5 \ A / \mu s \end{array} $	-	2	-	V/μs μs
t _q	Circuit commutated turn-off time		-	70	-	μs

BT151U series C

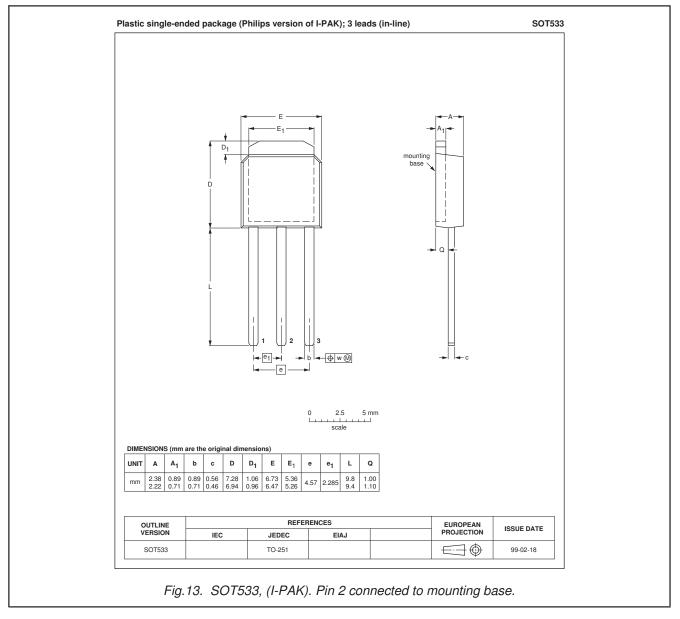


BT151U series C



BT151U series C

MECHANICAL DATA



Legal information

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Contact information

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